

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Kimiya MIYASHITA	05/07/2013
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13988555
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CH \$40.00 13988555

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ATTORNEY DOCKET NUMBER: 16454-000002/US/NP

NAME OF SUBMITTER: Dyanna M. Washington

Signature: /Dyanna M. Washington/

Date: 05/21/2013

Total Attachments: 2
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譲渡証(Translation/日本語訳)

下記に署名した私/私達、
は、

ある発明を創出し、これについて合衆国特許出願は

- ここに私/私達により署名され、
 _____に私/私達により(それぞれ)署名され、
 _____に出願され、出願番号 _____
 が交付され、
 PCT国際出願として、_____に出願され、
 出願番号 _____が交付され、

その発明は

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 及び全ての外国に於いて既に出願されたか若しくは今後出願
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 住所を有する _____、その後継者、譲受人
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 が単数ないしは複数の当該発明(以下当該発明という)に関わ
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 国に於いて出願し、特許を受けること；またこの譲渡証の意図
 と目的を誠実に実行することを求められた場合、下記に署名し
 た私/私達が、当該譲受人、その後継者、その被譲渡者、及び

Assignment

For good and valuable consideration, the receipt of which is hereby acknowledged, I/WE, the undersigned,

Kimiya MIYASHITA

who have created a certain invention for which an application for United States Letters Patent

- executed by ME/US on even date herewith,
 executed by ME/US on _____(respectively),
 filed on _____ and assigned Serial No. _____

filed as International Application No. PCT/JP2011/076512
 filed on November 17, 2011,

and entitled: CERAMIC HEAT SINK MATERIAL FOR
 PRESSURE CONTACT STRUCTURE,
 SEMICONDUCTOR MODULE USING THE SAME, AND
 METHOD FOR MANUFACTURING SEMICONDUCTOR
 MODULE

Do hereby sell, assign and transfer to KABUSHIKI KAISHA
 TOSHIBA and TOSHIBA MATERIALS CO.,LTD., a corporation of Japan, having a place of business at 1-1, Shibaura 1-Chome, Minato-Ku, Tokyo 105-8001 Japan and 8, Shinsugita-Cho, Isogo-Ku, Yokohama-Shi, Kanagawa-Ken 235-0032 Japan, respectively, its successors, assigns, and legal representatives, the full and exclusive right to said invention and said application and to any and all inventions described in said application for the United States, its territorial possessions and all foreign countries, and the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in the United States, its territorial possessions and all foreign countries; and in and to any and all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, and all other applications for Letters Patent relating thereto which have been or shall be filed in the United States, its territorial possessions and/or any foreign countries, and all rights, together with all priority rights, under any of the international conventions, unions, agreements, acts, and treaties, including all future conventions, unions, agreements, acts, and treaties;

Agree that KABUSHIKI KAISHA TOSHIBA and TOSHIBA MATERIALS CO.,LTD., hereinafter referred to as Assignee, may apply for and receive Letters Patent for said invention and said inventions, hereinafter referred to as said invention, in its own name, in the United States, its territorial possessions, and all foreign countries; and that, when requested to carry out in good faith the intent and purpose of this assignment, at the expense of said Assignee, its successors, assigns and legal representatives, the undersigned will execute all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, execute all rightful oaths, assignments, powers of attorney and other papers, testify in any legal or quasi legal proceedings; communicate to said Assignee, its successors, assigns or legal representatives all facts known to the undersigned relating to said invention and the history thereof; and generally do everything possible which said Assignee, its successors, assigns, or legal representatives shall consider desirable for aiding in securing, maintaining and enforcing proper patent protection for said invention and for vesting title to said invention and all applications for patents on said invention in said Assignee, its successors, assigns, or

<p>法定代理人の費用負担にて、一部継続出願、継続出願、分割出願、差替え出願、再発行出願、特許期間延長等を行い、合法的宣誓書、譲渡証、委任状等の書類を作成し、あらゆる法的または準法的訴訟手続に於いて証言を行うこと; 当該発明とその経緯に関連して、下記に署名した私/私達が知り得た全ての事実を、当該譲受人、後継者、被譲渡者、及び法定代理人に連絡すること; そして当該譲受人、後継者、被譲渡者、及び法定代理人が、当該発明の特許権の適切な保護、維持、権利行使するために望ましいと考慮すること、また、当該発明に関わる特許出願に際し、当該譲受人、後継者、被譲渡者、及び法定代理人に対して法的権限を付与することが望ましいと考慮することについて、可能な限り行うことを承諾する。</p> <p>そして、私/私達は、この書面により譲渡された権利や財産に影響する、如何なる譲渡、授權、抵当権、ライセンス等その他の協定も他の第三者との間で行っていないこと; 下記に署名した私/私達によって、この書面に記載されている権利が所有されていることを、当該譲受人、後継者、被譲渡者、及び法定代理人に対して誓約するものである。</p> <p>さらに、下記に署名した私/私達はこの譲渡書は英語の部分の表現によってのみ解釈されることに同意する。</p> <p>上記を証明するため、私/私達は下記日付で署名する。</p>	<p>legal representatives; and</p> <p>Covenant with said Assignee, its successors, assigns, or legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.</p> <p>I/WE, the undersigned do further agree that this Assignment is to be construed solely according to the terms of the English language portions thereof.</p> <p>IN TESTIMONY WHEREOF I/WE have hereunto set MY/OUR signature seal on the date indicated below.</p>
<p>唯一または第一発明者の氏名</p>	<p>Full name of sole or first inventor Kimiya MIYASHITA</p>
<p>発明者の署名 日付</p>	<p>Inventor's signature Date <i>Kimiya Miyashita</i> May 7, 2013</p>
<p>第二共同発明者の氏名(いる場合)</p>	<p>Full name of second joint inventor, if any</p>
<p>第二共同発明者の署名 日付</p>	<p>Second Inventor's signature Date</p>
<p>第三共同発明者の氏名(いる場合)</p>	<p>Full name of third joint inventor, if any</p>
<p>第三共同発明者の署名 日付</p>	<p>Third Inventor's signature Date</p>
<p>第四共同発明者の氏名(いる場合)</p>	<p>Full name of fourth joint inventor, if any</p>
<p>第四共同発明者の署名 日付</p>	<p>Fourth Inventor's signature Date</p>